

# CHINVAY

## APPROVAL SHEET

CUSTOMER :

ITME : 6PIN 方型 SIM 卡座

MODEL : SC-2.54- 6C20SMT

MATERIEL NO:

DATE : 08/08/2007

APPROVED BY:

### 深圳市创宇伟业科技有限公司

地 址： 深圳市龙岗区葵冲镇奔康工业区 B-7 栋 3 楼

电 话： 0755-8977 3388 8312 0030

传 真： 0755-8312 0032 8977 5511

网 站： [www.chinvay.com](http://www.chinvay.com)

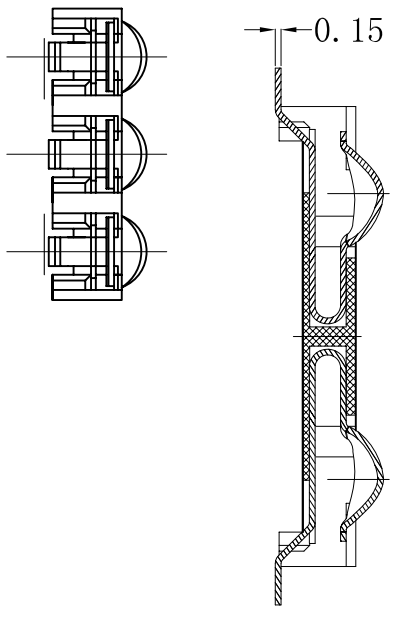
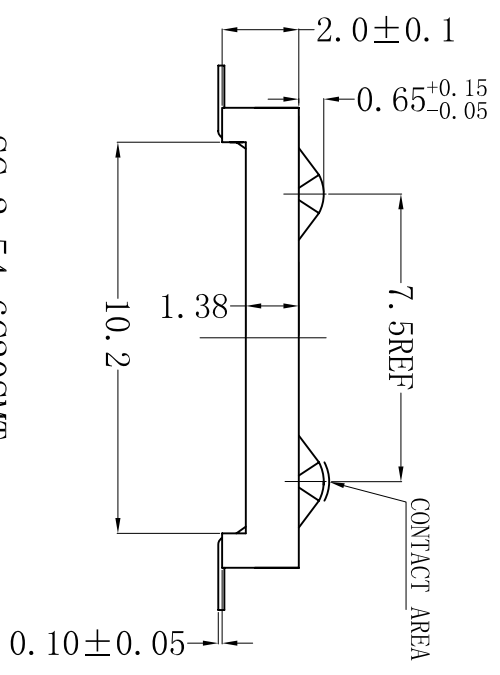
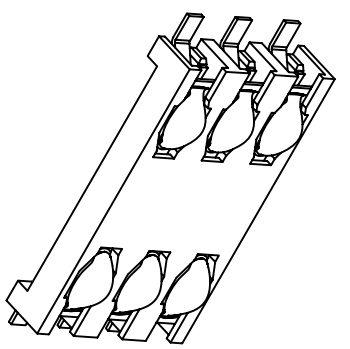
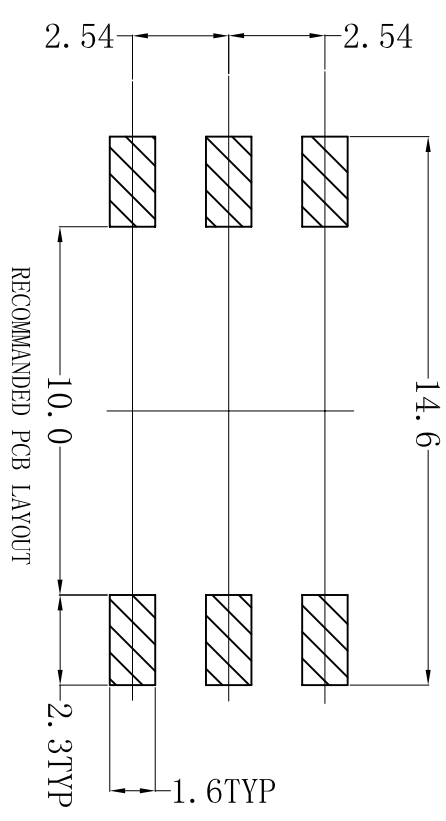
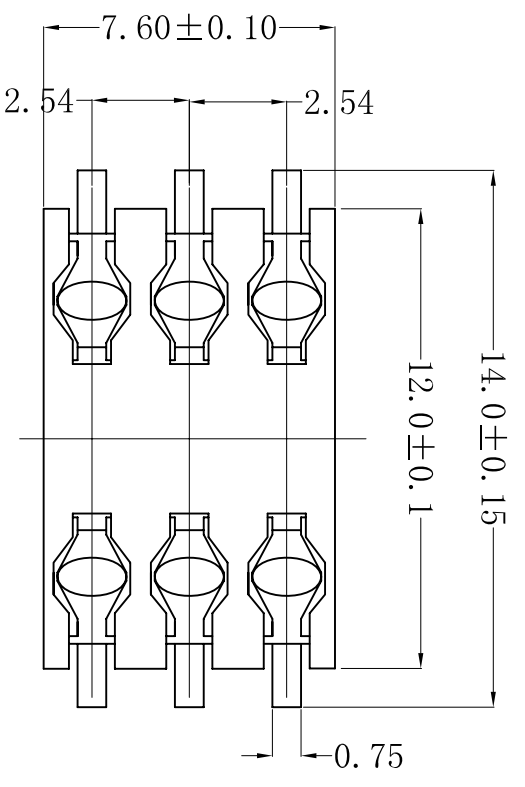
阿里巴巴： [cywy01.cn.alibaba.com](http://cywy01.cn.alibaba.com)

销售经理： 胡先生 手机： 136 0251 1930

邮 件 I： [hkn@chinvay.com](mailto:hkn@chinvay.com)

邮 件 II： [hukn999@163.com](mailto:hukn999@163.com)

| REV. | ECN NO. | LOCATION | DESCRIPTION | DATE     | DESIGN |
|------|---------|----------|-------------|----------|--------|
| V0.1 |         |          |             | 18/07/07 |        |



- NOTES:
- Material :  
Housing: Thermoplastic UL94V-0 color black;  
Contact: Copper alloy gold plating;
  - All dimensions are in millimeters.
  - Electrical performances  
Rating: AC 30V 0.5A MAX  
Contact resistant: 50mΩ MAX  
Insulation resistant: 100MΩ  
Withstand voltage: AC 250V 1min
  - Mechanical performances  
Range: -40 ~ 85°C  
Operation force: 40gf min  
Lift test: 5000 cycles

SC-2.54-6C20SMT  
 Sim card  
 Pitch header  
 Position  
 Connection type  
 Gold Plating 20u"

| DIM  | TOL   | DIM  | TOL |
|------|-------|------|-----|
| X    | ±0.20 | X    | ±2° |
| .X   | ±0.10 | .X   | ±1° |
| .XX  | ±0.03 | .XX  | ±1° |
| .XXX | ±0.02 | .XXX | ±1° |

|                           |      |             |                                 |       |         |
|---------------------------|------|-------------|---------------------------------|-------|---------|
| 2                         |      | CONTACT     | COPPER ALLOY, 20u" GOLD PLATING | 6     |         |
| 1                         |      | HOUSING     | L. C. P, BLACK                  | 1     |         |
| ITEM                      |      | DESCRIPTION | MATERIAL                        | Q' TY | REMARKS |
| <br><b>深圳市创宇伟业科技有限公司</b>  |      |             |                                 |       |         |
| DRAW NO.                  |      | DESIGN:     | DATE                            |       |         |
| 3020008                   |      | CHECK:      |                                 |       |         |
| REV.                      | V0.1 | APPROVAL:   |                                 |       |         |
| TITLE: SIM CARD CONNECTOR |      |             | P/N: SC-2.54-6C20SMT            |       |         |
| SHEET: 1/1                |      |             | SCALE: 1:1                      |       |         |
| UNIT: mm                  |      |             |                                 |       |         |



# 规格书

|             |                    |             |               |                |
|-------------|--------------------|-------------|---------------|----------------|
| 系列类型        | SIM CARD CONNECTOR | 编写 WRTN BY: | 审核 CHECKED BY | 批准 APPROVED BY |
| 型号          | SC-2.54-6C20SMT    | Chen Ming   | Zhang BO      | Wang Wei       |
| VERSION 版本: | V0.1               |             |               |                |
| DATE 日期:    | 2007.04.15         | 2007.04.10  | 2007.04.12    | 2007.04.15     |

1. SCOPE 适用范围 本规格书适用:“SIM CARD CONNECTOR”系列 This specification covers the requirements for: “SIM CARD CONNECTOR”

2. Rating 额定值: DC 30V 0.5A

3. CONSTRUCTION 构造

3.1 Shape and dimensions are subject to drawing. 形状.尺寸根据图面确定.

3.2 All part not allowed to exist rust 、 crack and poor planting.各部分无生锈、裂痕、电镀不良现象.

4. Standard test conditions shall be 5 to 35°C in temperature and 45 TO 85% in humidity.

温度 5~35°C , 湿度 45~85% 标准状态下测试。

| Item 项目 | Test condition 测试条件 | Performance 规格 |
|---------|---------------------|----------------|
|---------|---------------------|----------------|

5. Electronical performance 电气性能

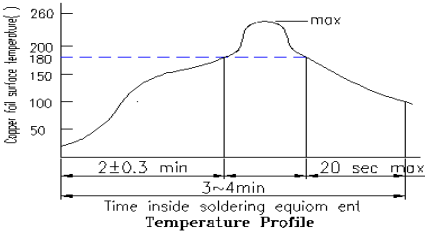
|     |                            |  |                                      |
|-----|----------------------------|--|--------------------------------------|
| 5.1 | Contact resistance 接触阻抗    | Being measured at 1 KHz small current contact resistance meter. 在1kHz 小电流下测量。  | 50mΩ max.<br>50 毫欧 以下。               |
| 5.2 | Insulation resistance 绝缘阻抗 | Measurements shall be made following application of DC 500 V potential across terminals and across terminals and frame for 1 minute. 在端子之间和端子与壳之间加 DC 500 V 条件下,持续 1 分钟测量。 | 100MΩ min.<br>100 兆欧 以上。             |
| 5.3 | Withstand voltage 耐电压      | AC 250 V(50Hz or 60 Hz)shall be applied across terminals and across terminals and frame for one minute. 在端子之间和端子与壳之间加 AC 250 V (50Hz 或 60Hz)条件下,持续 1 分钟测量。                 | There shall be no breakdown 无击穿现象出现. |

6. Mechanical performance 机械性能

|     |                      |                 |                     |
|-----|----------------------|-----------------|---------------------|
| 6.1 | Operating force 接触压力 |                 | 40gf MIN<br>40gf 以上 |
| 6.2 | Range 使用温度范围         | 在-40~+85°C温度内使用 |                     |

7. Durability 耐久性

|     |                    |   |   |
|-----|--------------------|---|---|
| 7.1 | Lift test 寿命试验     | 5,000 cycles of operation at a rate of 15-18 cycles per minute with unloading 在无负载条件下,以每分钟 15—18 次的速度操作 5,000 次。                    | (1) Contact resistance 接触阻抗 200mΩ max.200 毫欧 以下<br>(2) 其它满足机械,电器性能. |
| 7.2 | Heat test 耐热试验     | 85±2°C for 96 hours, test after keeping in normal condition for 60 minutes. 在 85±2°C环境中放 96 小时,再放在正常环境中, 60 分钟后进行测试。                | Insulation resistance 50MΩ min.50 兆欧以上, 其它满足机械,电器性能.                |
| 7.3 | Humidity test 耐湿试验 | 40±2°C 90-95%RH for 96 hours, test after keeping in normal condition for 60 min. 在 40±2°C 90—95%RH 环境中放 96 小时,再放在正常环境中, 60 分钟后进行测试。 | Insulation resistance 50MΩ min.50 兆欧以上, 其它满足机械,电器性能.                |

|     |  |   |  |
|-----|--|---|--|
| 7.4 | Cold test<br>耐冷试验                          | At $-25 \pm 3^{\circ}\text{C}$ for 96 hours, test after keeping in normal condition for 60 min. 在 $-25 \pm 3^{\circ}\text{C}$ 环境中放 96 小时, 再放在正常环境中, 60 分钟后进行测试。   | There shall be no sign of damage mechanically and electrically 无任何迹象显示机械及电气性能损坏。   |
| 7.5 | Resistance to soldering heat test<br>耐焊性试验 | <p>soldering iron method:<br/>Bit temperature <math>350 \pm 10^{\circ}\text{C}</math> application time <math>3 \pm 0.5</math> sec application time <math>3 \pm 0.5</math> sec. However excessive pressure shall not be applied to the terminal. 手焊接的时候温度需控制在 <math>350 \pm 10^{\circ}\text{C}</math>, 时间为 <math>3 \pm 0.5</math> 秒, 不能在排脚上施加异常压力。</p> <p>Reflow Soldering Conditions:<br/>Preheat: Temperature on the copper foil surface should reach <math>180^{\circ}\text{C}</math> <math>2 \pm 0.3</math> minutes after the P.W.B entered into the soldering equipment. Soldering heat: Temperature on the copper foil surface should reach the peak temperature of <math>260^{\circ}\text{C}</math> with in 10 seconds after the P.W.B enter into soldering heat zone.<br/>过回流焊条件:<br/>预热: 电镀层表面的温度应达到 <math>180^{\circ}\text{C}</math>, <math>2 \pm 0.3</math> 分钟, 后电路板进入回流焊设备. 回流焊温度: 电镀层表面温度最高为 <math>260^{\circ}\text{C}</math> 且停留不超过 10 秒后电路板进入低温焊接处。</p>  | Without deformation of case or excessive looseness of terminals electrical characteristics shall be satisfied. 本体无变形, 能满足于机械、电气性能。 |

附: 产品照片

